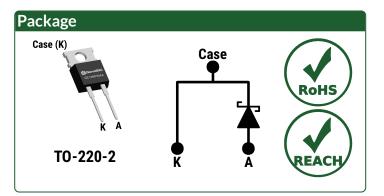
Silicon Carbide Schottky Diode



 V_{RRM} 650 V $I_{F(T_C = 154^{\circ}C)} =$ 12 A 30 nC Qc

Features

- Revolutionary Low Built-In Voltage (VBI)
- Gen5 Thin Chip Technology for Low V_F
- Superior Figure of Merit Qc * VF
- Enhanced Surge Current Robustness Low Thermal Resistance
- Zero Reverse Recovery
- 100% Avalanche (UIL) Tested
- Excellent dV/dt Ruggedness



Advantages

- Low Conduction Losses for All Load Conditions
- Optimal Price Performance
- Increased System Power Density
- High System Reliability
- Reduced Cooling Requirements
- Temperature Independent Fast Switching
- Easy to Parallel without Thermal Runaway

Applications

- Switched Mode Power Supply (SMPS)
- Solar Inverter
- Server and Telecom Power Supply
- **Battery Charger**
- Uninterruptible Power Supply (UPS)
- Motor Control
- Power Factor Correction (PFC)

Absolute Maximum Ratings (At T _C = 25°C Unless Otherwise Stated)								
Parameter	Symbol	Conditions	Values	Unit	Note			
Repetitive Peak Reverse Voltage	V_{RRM}		650	٧				
Continuous Forward Current	lF	$T_C = 100^{\circ}C, D = 1$	25					
		$T_C = 135^{\circ}C$, D = 1	18	Α	Fig. 4			
		$T_C = 154^{\circ}C, D = 1$	12					
Non-Repetitive Peak Forward Surge Current, Half Sine Wave	Iғ,sм	T_C = 25°C, t_P = 10 ms	84	Α				
		T_C = 150°C, t_P = 10 ms	67					
Repetitive Peak Forward Surge Current, Half Sine Wave	I _{F,RM}	T_C = 25°C, t_P = 10 ms	50	Α				
Repetitive Feak I of Ward Surge Current, Trail Sille Wave		T_C = 150°C, t_P = 10 ms	35	Α				
Non-Repetitive Peak Forward Surge Current	I _{F,MAX}	T_C = 25°C, t_P = 10 μ s	420	Α				
i ² t Value	∫i²dt	$T_C = 25^{\circ}C$, $t_P = 10 \text{ ms}$	35	A ² s				
Non-Repetitive Avalanche Energy	E _{AS}	L = 2.2 mH, I _{AS} = 12 A	157	mJ				
Diode Ruggedness	dV/dt	V _R = 0 ~ 520 V	200	V/ns				
Power Dissipation	P _{TOT}	T _C = 25°C	151	W	Fig. 3			
Operating and Storage Temperature	T_j , T_{stg}		-55 to 175	°C				



Electrical Characteristics	;							
Parameter	Symbol	Conditions -		Values			Unit	Note
	Зуший			Min.	Тур.	Max.	Ullit	Note
Diode Forward Voltage	V _F	I _F = 12 A, T _j = 25°C			1.25	1.4	٧	Fig. 1
	VF	I _F = 12 A, T _j = 175°C			1.75			
Reverse Current	l _n	$V_R = 650 \text{ V, } T_j = 25^{\circ}\text{C}$			1	10	μΑ	Fig. 2
	IR	$V_R = 650 \text{ V, } T_j = 175^{\circ}\text{C}$			232			
Total Capacitive Charge	Qc		$V_{R} = 200 \text{ V}$		20	nC		Fig. 7
	Qυ	I _F ≤ I _{F,MAX} dI _F /dt = 200 A/µs	$V_{R} = 400 V$		30		110	1 ig. 7
Switching Time	t _o		$V_R = 200 \text{ V}$		< 10		ns	
	ts		$V_{R} = 400 \text{ V}$		\ 10		115	
Total Capacitance	С	V_R = 1 V, f = 1MHz V_R = 400 V, f = 1MHz			559		nE	Fig. 6
					39		pF 	

Thermal/Package Characteristics								
Parameter	Symbol	Conditions	Values			Heit	Note	
			Min.	Тур.	Max.	- Unit	Note	
Thermal Resistance, Junction - Case	R_{thJC}			1.0		°C/W	Fig. 9	
Weight	W _T			2.0		g		
Mounting Torque	T _M	Screws to Heatsink			1.0	Nm		





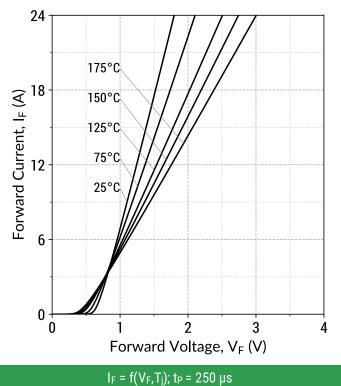
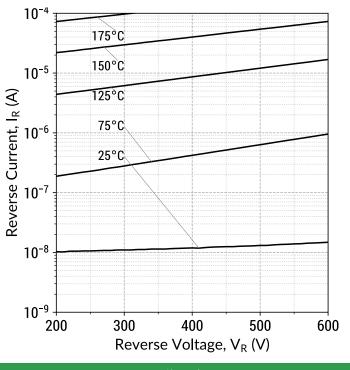


Figure 2: Typical Reverse Characteristics



 $I_R = f(V_R, T_j)$

Figure 3: Power Derating Curves

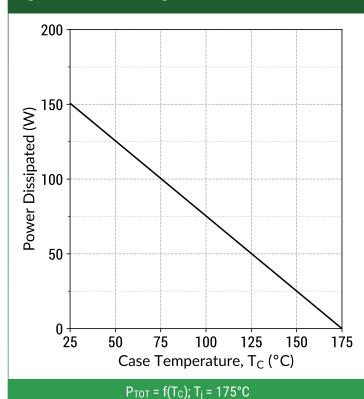
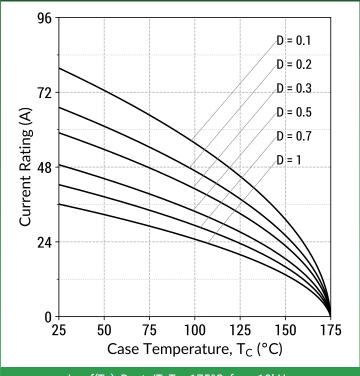


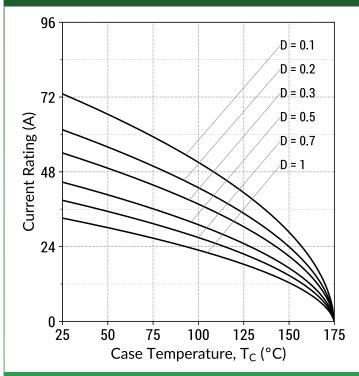
Figure 4: Current Derating Curves (Typical V_F)



 $I_F = f(T_C)$; D = t_P/T ; $T_j \le 175$ °C; $f_{SW} > 10$ kHz

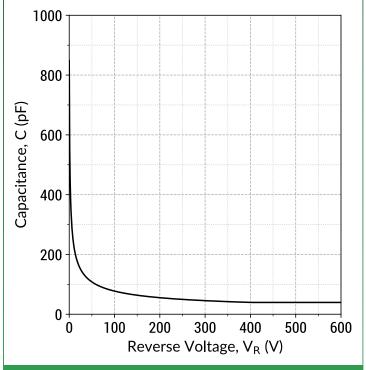


Figure 5: Current Derating Curves (Maximum V_F)



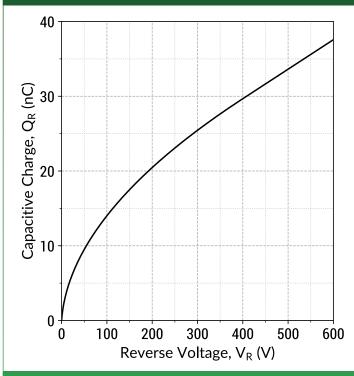
 $I_F = f(T_C)$; D = t_P/T ; $T_j \le 175$ °C; $f_{SW} > 10$ kHz

Figure 6: Typical Junction Capacitance vs Reverse Voltage Characteristics



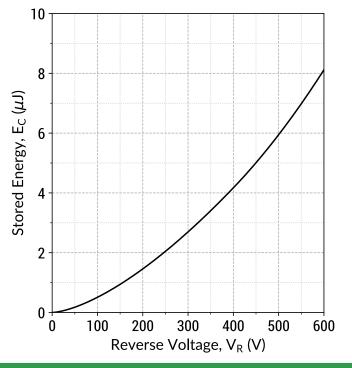
 $C = f(V_R)$; f = 1MHz

Figure 7: Typical Capacitive Charge vs Reverse Voltage Characteristics



 $Q_C = f(V_R)$; f = 1MHz

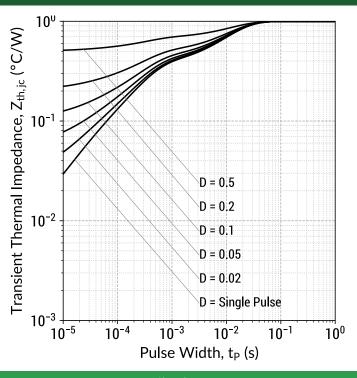
Figure 8: Typical Capacitive Energy vs Reverse Voltage Characteristics



 $E_C = f(V_R); f = 1MHz$

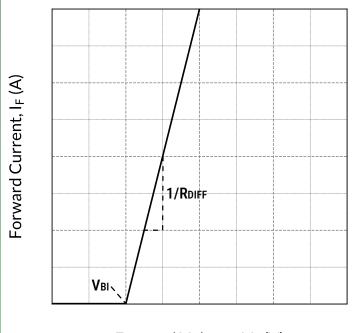


Figure 9: Transient Thermal Impedance



 $Z_{th,jc} = f(t_P,D); D = t_P/T$

Figure 10: Forward Curve Model



Forward Voltage, $V_F(V)$

 $I_F = f(V_F, T_j)$

Forward Curve Model Equation:

 $I_F = (V_F - V_{BI})/R_{DIFF} (A)$

Built-In Voltage (V_{BI}):

$$V_{BI}(T_j) = m \times T_j + n (V)$$

 $m = -0.00124 (V/^{\circ}C)$
 $n = 0.72 (V)$

Differential Resistance (RDIFF):

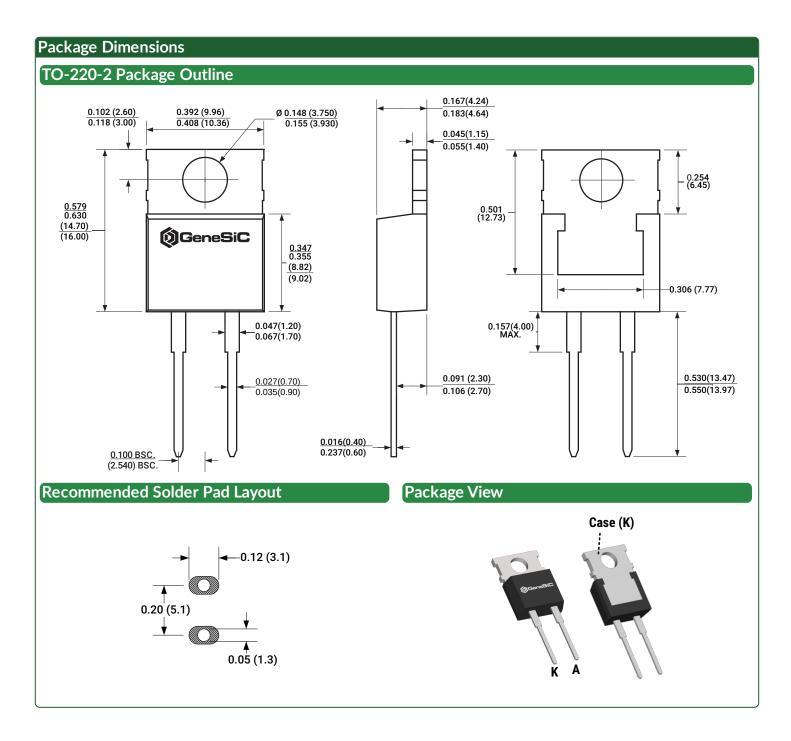
$$R_{DIFF}(T_j) = a \times T_j^2 + b \times T_j + c (\Omega)$$

 $a = 8.02e-07 (\Omega/^{\circ}C^2)$
 $b = 0.000227 (\Omega/^{\circ}C)$
 $c = 0.0401 (\Omega)$

Forward Power Loss Equation:

$$P_{LOSS} = V_{BI}(T_j) \times I_{AVG} + R_{DIFF}(T_j) \times I_{RMS}^2$$





NOTE

- 1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
- 2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS.





Compliance

RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS 2), as adopted by EU member states on January 2, 2013 and amended on March 31, 2015 by EU Directive 2015/863. RoHS Declarations for this product can be obtained from your GeneSiC representative.

REACH Compliance

REACH substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a GeneSiC representative to insure you get the most up-to-date REACH SVHC Declaration. REACH banned substance information (REACH Article 67) is also available upon request.

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SPICE Models: https://www.genesicsemi.com/sic-schottky-mps/GE12MPS06A/GE12MPS06A_SPICE.zip
 PLECS Models: https://www.genesicsemi.com/sic-schottky-mps/GE12MPS06A/GE12MPS06A_PLECS.zip
 CAD Models: https://www.genesicsemi.com/sic-schottky-mps/GE12MPS06A/GE12MPS06A_3D.zip

• Evaluation Boards: https://www.genesicsemi.com/technical-support

Reliability: https://www.genesicsemi.com/reliability
 Compliance: https://www.genesicsemi.com/compliance
 Quality Manual: https://www.genesicsemi.com/quality

Revision History

Rev 21/Jun: Updated with most recent test data

· Supersedes: Rev 20/Jul



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